



electronica 2014
inside tomorrow



Test Research, Inc. (TRI) invites you to visit booth **A1 275** at **electronica 2014** trade show in Munich between **November 11-14** for a personal tour of the latest inspection and testing solutions from TRI.



TR7007 SII Plus 3D SPI

Super high speed 3D SPI with ultra high resolution for reliable, easy to use inspection and SPC production analysis.



TR7007Q 3D SPI

Compact 3D SPI with fast Stop-and-Go design for ultimate accuracy and easy to use high performance inspection and analysis.



TR7500 SIII 3D AOI

State-of-the-Art 3D AOI with the best of 2D and 3D technologies for any inspection requirements.



TR7600 SII 3D AXI with CT

Inline 3D AXI just got better with on-demand 3D CT imaging for the most demanding applications.



TR5001 SII TINY ICT

World's most powerful compact ICT designed to test any aspect of your PCBs at an unbeatable price.